

# **ZXTN25100DG** 100V NPN high gain transistor in SOT223

### Summary

 $BV_{CEX} > 180V$ 

 $BV_{CEO} > 100V$ 

 $BV_{ECO} > 6V$ 

 $I_{C(cont)} = 3A$ 

V<sub>CE(sat)</sub> < 100mV @ 1A

 $R_{CE(sat)} = 85m\Omega$ 

 $P_{D} = 3.0W$ 



### Complementary part number ZXTP19100CG

### **Description**

Packaged in the SOT223 outline this new low saturation NPN transistor offers extremely low on state losses making it ideal for use in DC-DC circuits and various driving and power management functions.

### **Features**

- · High power dissipation SOT223 package
- · High gain
- Low saturation voltage
- 180V forward blocking voltage
- · 6V reverse blocking voltage

### **Applications**

- · PSU start up circuit
- · DC DC converters
- · Motor drive
- · Relay, lamp and solenoid drive

# **Ordering information**

Device	Reel size (inches)	Tape width (mm)	Quantity per reel	
ZXTN25100DGTA	7	12	1000	

# ΠE Πв

Pinout - top view

### **Device marking**

ZXTN25 100D

### **Absolute maximum ratings**

Parameter	Symbol	Limit	Unit
Collector-Base voltage	V <sub>CBO</sub>	180	V
Collector-Emitter voltage (forward blocking)	V <sub>CEX</sub>	180	V
Collector-Emitter voltage	$V_{CEO}$	100	V
Emitter-Collector voltage (reverse blocking)	V <sub>ECO</sub>	6	V
Emitter-Base voltage	V <sub>EBO</sub>	7	V
Continuous Collector current <sup>(c)</sup>	I <sub>C</sub>	3	Α
Base current	I <sub>B</sub>	1	Α
Peak pulse current	I <sub>CM</sub>	3.5	Α
Power dissipation at T <sub>A</sub> =25°C <sup>(a)</sup>	$P_{D}$	1.2	W
Linear derating factor		9.6	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(b)</sup>	$P_{D}$	1.6	W
Linear derating factor		12.8	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(c)</sup>	$P_{D}$	3	W
Linear derating factor		24	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(d)</sup>	$P_{D}$	5.3	W
Linear derating factor		42	mW/°C
Power dissipation at T <sub>C</sub> =25°C <sup>(e)</sup>	$P_{D}$	7.3	W
Linear derating factor		58	mW/°C
Operating and storage temperature range	T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

### Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient <sup>(a)</sup>	$R_{\Theta JA}$	104	°C/W
Junction to ambient <sup>(b)</sup>	$R_{\Theta JA}$	78	°C/W
Junction to ambient <sup>(c)</sup>	$R_{\Theta JA}$	42	°C/W
Junction to ambient <sup>(d)</sup>	$R_{\Theta JA}$	23.5	°C/W
Junction to case <sup>(e)</sup>	$R_{\Theta JC}$	16	°C/W

#### NOTES:

<sup>(</sup>a) For a device surface mounted on 15mm x 15mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

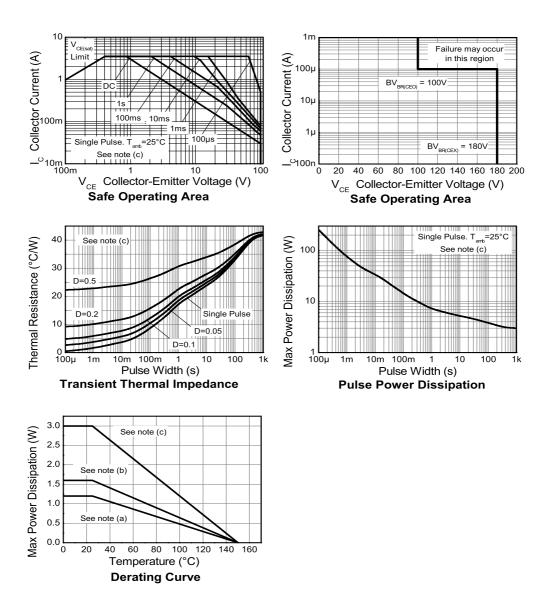
<sup>(</sup>b) Mounted on 25mm x 25mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

<sup>(</sup>c) Mmounted on 50mm x 50mm x 0.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.

<sup>(</sup>d) As (c) above measured at t<5 seconds.

<sup>(</sup>e) Junction to case (collector tab). Typical

### Thermal characteristics



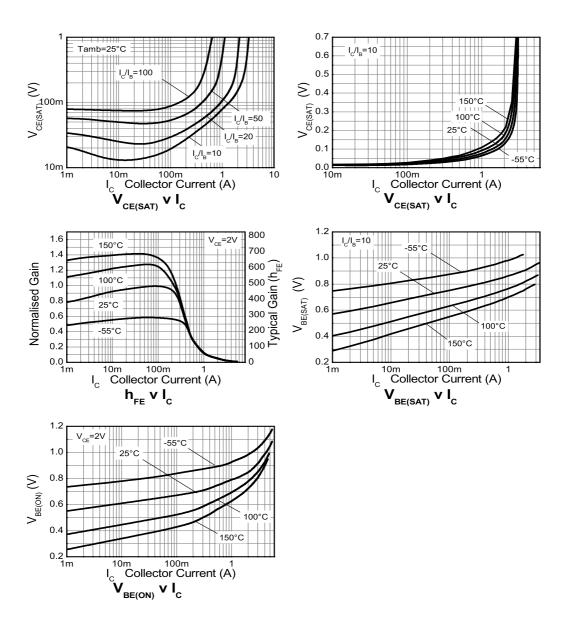
### Electrical characteristics (at T<sub>amb</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Collector-Base breakdown voltage	BV <sub>CBO</sub>	180	220		V	I <sub>C</sub> = 100μA
Collector-Emitter breakdown voltage (forward blocking)	BV <sub>CEX</sub>	180	220		V	$I_C$ = 100μA, $R_{BE}$ < 1kΩ or -1V < $V_{BC}$ < 0.25V
Collector-Emitter breakdown voltage	BV <sub>CEO</sub>	100	130		V	I <sub>C</sub> = 10mA <sup>(*)</sup>
Emitter-Collector breakdown voltage (reverse blocking)	BV <sub>ECX</sub>	6	8.2		V	$I_E = 100 \mu A$ , $R_{BC} < 1 k\Omega$ or 0.25V > $V_{BC} > -0.25 V$
Emitter-Collector breakdown voltage (reverse blocking)	BV <sub>ECO</sub>	6	8.7		V	$I_E = 100 \mu A$
Emitter-Base breakdown voltage	BV <sub>EBO</sub>	7	8.3		V	I <sub>E</sub> = 100μA
Collector-Base cut-off	$I_{CBO}$		<1	50	nA	V <sub>CB</sub> =180V
current				0.5	μΑ	V <sub>CB</sub> =180V, T <sub>amb</sub> =100°C
Collector-Emitter cut-off current	I <sub>CEX</sub>			100	nA	$V_{CE} = 100V, R_{BE} < 1k\Omega$ or $-1V < V_{BE} < 0.25V$
Emitter-Base cut-off current	I <sub>EBO</sub>		<1	50	nA	V <sub>EB</sub> = 5.6V
Collector-Emitter	$V_{CE(sat)}$		120	170	mV	$I_C = 0.5A$ , $I_B = 10mA^{(*)}$
saturation voltage			80	100	mV	$I_C = 1A$ , $I_B = 100 \text{mA}^{(*)}$
			215	345	mV	$I_C = 2.5A$ , $I_B = 250mA^{(*)}$
			200	500	mV	$I_C = 3A$ , $I_B = 600 \text{mA}^{(*)}$
Base-Emitter saturation voltage	V <sub>BE(sat)</sub>		1020	1100	mV	$I_C = 3A$ , $I_B = 600 \text{mA}^{(*)}$
Base-Emitter turn-on voltage	V <sub>BE(on)</sub>		905	1000	mV	$I_C = 3A, V_{CE} = 2V^{(*)}$
Static forward current	h <sub>FE</sub>	300	450	900		$I_C = 10 \text{mA}, V_{CE} = 2V^{(*)}$
transfer ratio		120	170			$I_C = 0.5A, V_{CE} = 2V^{(*)}$
		40	60			$I_C = 1A, V_{CE} = 2V^{(*)}$
			10			$I_C = 3A, V_{CE} = 2V^{(*)}$
Transition frequency	f <sub>T</sub>		175		MHz	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 10V f = 100MHz
Input capacitance	C <sub>ibo</sub>		154	250	pF	$V_{EB} = 0.5V, f = 1MHz^{(*)}$
Output capacitance	C <sub>obo</sub>		8.7	15	pF	V <sub>CB</sub> = 10V, f = 1MHz <sup>(*)</sup>
Delay time						
Rise time	t <sub>d</sub>		16.4		ns	
11100 111110	t <sub>d</sub> t <sub>r</sub>		16.4 115		ns ns	$I_C = 500 \text{mA}, V_{CC} = 10 \text{V},$
Storage time						$I_{C} = 500 \text{mA}, V_{CC} = 10 \text{V},$ $I_{B1} = -I_{B2} = 50 \text{mA}$

#### NOTES:

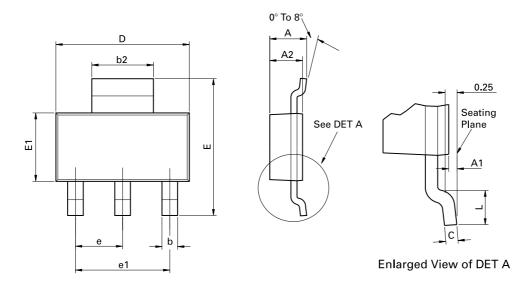
<sup>(\*)</sup> Measured under pulsed conditions. Pulse width  $\leq$  300µs; duty cycle  $\leq$  2%.

### **Typical characteristics**



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### Package outline - SOT223



Conforms to JEDEC TO-261 AA Issue B

Dim.	Millin	neters	Inc	hes	Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.	Diiii.	Min.	Max.	Min.	Max.
Α	-	1.80	-	0.071	D	6.30	6.70	0.248	0.264
A1	0.02	0.10	0.0008	0.004	е	2.30	BSC	0.090	5 BSC
A2	1.55	1.65	0.0610	0.0649	e1	4.60	BSC	0.181	BSC
b	0.66	0.84	0.026	0.033	E	6.70	7.30	0.264	0.287
b2	2.90	3.10	0.114	0.122	E1	3.30	3.70	0.130	0.146
С	0.23	0.33	0.009	0.013	L	0.90	-	0.355	-

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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